Dual 2-Input Exclusive-OR Gate

The NLX2G86 is a high performance dual 2-input Exclusive-OR Gate operating from a 1.65 V to 5.5 V supply.

Features

- Extremely High Speed: t_{PD} 2.4 ns (typical) at V_{CC} = 5.0 V
- Designed for 1.65 V to 5.5 V V_{CC} Operation
- Over Voltage Tolerant Inputs and Outputs
- LVTTL Compatible Interface Capability With 5.0 V TTL Logic with V_{CC} = 3.0 V
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current Substantially Reduces System Power Requirements
- Replacement for NC7WZ86
- This is a Pb-Free Device

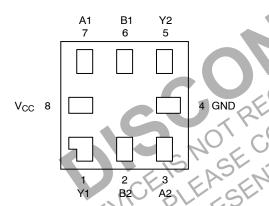


Figure 1. Pinout (Top View)

PIN ASSIGNMENT

Pin	Function
1	Y1
2	B2
3	A2
4	GND
5	Y2
6	B1
7	A1
8	V _{CC}



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MARKING DIAGRAM

UQFN8 MU SUFFIX CASE 523AN



AC = Device Code

M = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

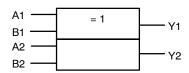


Figure 2. Logic Symbol

FUNCTION TABLE

Inp	Output Y = A + B	
Α	В	Υ
L	L	L
L	Н	Н
Н	L	Н
Н	Н	L

MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
VI	DC Input Voltage		-0.5 to +7.0	V
Vo	DC Output Voltage		-0.5 to +7.0	V
I _{IK}	DC Input Diode Current	V _I < GND	-50	mA
I _{OK}	DC Output Diode Current	V _O < GND	-50	mA
Io	DC Output Sink Current		±50	mA
I _{CC}	DC Supply Current per Supply Pin		±100	mA
I _{GND}	DC Ground Current per Ground Pin		±100	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
T_{J}	Junction Temperature under Bias		+150	°C
$\theta_{\sf JA}$	Thermal Resistance	(Note 1)	TBD (C)	°C/W
P _D	Power Dissipation in Still Air at 85°C		TBD	mW
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V _{ESD}		nan Body Model (Note 2) Machine Model (Note 3) d Device Model (Note 4)	> 2000 > 200 N/A	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- device reliability.

 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace with no air flow.

 2. Tested to EIA/JESD22-A114-A.

 3. Tested to EIA/JESD22-A115-A.

 4. Tested to JESD22-C101-A.

 RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	Supply Voltage Operating Data Retention Only		5.5 5.5	V
VI	Input Voltage (Note 5	0	5.5	V
Vo	Output Voltage (HIGH or LOW State	0	5.5	V
T _A	Operating Free-Air Temperature	-40	+ 125	°C
Δt/ΔV	Input Transition Rise or Fall Rate $\begin{array}{c} V_{CC} = 1.8 \ V \pm 0.15 \ V_{CC} = 2.5 \ V \pm 0.2 \ V_{CC} = 3.0 \ V \pm 0.3 \ V_{CC} = 5.0 \ V \pm 0.5 \ V_{CC} = 5.0 \ V_{$	0 0	20 20 10 5	ns/V

^{5.} Unused inputs may not be left open. All inputs must be tied to a high- or low-logic input voltage level.

DC ELECTRICAL CHARACTERISTICS

		V _{CC}	T _A = 25°C		$-40^{\circ}\text{C} \leq \text{T}_{\text{A}} \leq 85^{\circ}\text{C}$				
Symbol	Parameter	(V)	Min	Тур	Max	Min	Max	Unit	Condition
V _{IH}	High-Level Input Voltage	1.65 to 1.95 2.3 to 5.5	0.75 V _{CC} 0.7 V _{CC}			0.75 V _{CC} 0.7 V _{CC}		٧	
V _{IL}	Low-Level Input Voltage	1.65 to 1.95 2.3 to 5.5			0.25 V _{CC} 0.3 V _{CC}		0.25 V _{CC} 0.3 V _{CC}	٧	
V _{OH}	High-Level Output Voltage V _{IN} = V _{IH}	1.65 1.8 2.3 3.0 4.5	1.55 1.7 2.2 2.9 4.4	1.65 1.8 2.3 3.0 4.5		1.55 1.7 2.2 2.9 4.4		V	I _{OH} = -100 μA
		1.65 2.3 3.0 3.0 4.5	1.29 1.9 2.4 2.3 3.8	1.52 2.15 2.80 2.68 4.20		1.29 1.9 2.4 2.3 3.8		V	I _{OH} = -4 mA I _{OH} = -8 mA I _{OH} = -16 mA I _{OH} = -24 mA I _{OH} = -32 mA
V _{OL}	Low-Level Output Voltage V _{IN} = V _{IL}	1.65 1.8 2.3 3.0 4.5		0.0 0.0 0.0 0.0 0.0	0.1 0.1 0.1 0.1 0.1		0.1 0.1 0.1 0.1 0.1	V	I _{OL} = 100 µA
		1.65 2.3 3.0 3.0 4.5		0.08 0.10 0.15 0.22 0.22	0.24 0.30 0.40 0.55 0.55	FC	0.24 0.30 0.40 0.55 0.55		I _{OL} = 4 mA I _{OL} = 8 mA I _{OL} = 16 mA I _{OL} = 24 mA I _{OL} = 32 mA
I _{IN}	Input Leakage Current	0 to 5.5			±1.0		±1.0	μΑ	$0 \text{ V} \leq V_{IN} \leq 5.5 \text{ V}$
l _{OFF}	Power Off Leakage Current	0.0			FO	URC	RAO	μΑ	V _{IN} or V _{OUT} = 5.5 V
I _{CC}	Quiescent Supply Current	1.65 to 5.5			1:0	MF	10	μΑ	V _{IN} = 5.5 V, GND

AC ELECTRICAL CHARACTERISTICS t_R = t_F = 3.0 ns

		MO 2 0 7	V _{CC}	T	A = 25°	С	-40°C ≤ T	A ≤ 125°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
t _{PLH}	Propagation Delay	$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	1.8 ± 0.15	2.0	7.9	9.0	2.0	10.5	ns
t _{PHL}	(Figure 3 and 4)	$R_L = 1 M\Omega$, $C_L = 15 pF$	2.5 ± 0.2	1.2	4.1	7.0	1.2	7.5	
	c Dr	$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	3.3 ± 0.3	0.8	3.0	4.8	0.8	5.2	
	MIS BY	R_L = 500 Ω, C_L = 50 pF		1.2	3.8	5.4	1.2	5.9	
		$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	5.0 ± 0.5	0.5	2.2	3.5	0.5	3.8	
		$R_L = 500 \Omega, C_L = 50 pF$		0.8	2.9	4.2	1.0	4.6	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	$V_{CC} = 5.5 \text{ V}, V_I = 0 \text{ V or } V_{CC}$	2.5	pF
C _{PD}	Power Dissipation Capacitance	10 MHz, V _{CC} = 3.3 V, V _I = 0 V or V _{CC}	9	pF
	(Note 6)	10 MHz, $V_{CC} = 5.5 \text{ V}$, $V_{I} = 0 \text{ V or } V_{CC}$	11	

^{6.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

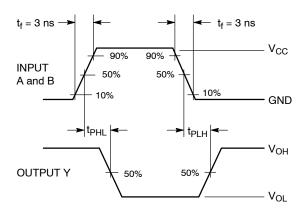
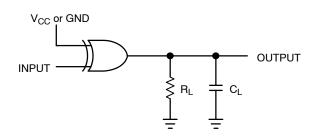


Figure 3. Switching Waveform



A 1-MHz square input wave is recommended for propagation delay tests.

Figure 4. Test Circuit

DEVICE ORDERING INFORMATION

Device Order Number	Package Type	Tape and Reel Size [†]
NLX2G86MUTCG	UQFN8 (Pb-Free)	3000 Units / Tape & Reel
For information on tape and reel specifications, Specifications Brochure, BRD8011/D.		es, please refer to our Tape and Reel Packaging
	ED	FORMATION FORMATION
	MENDU	CRINK
	COMMITTON	AFO.
CU	RECOMMENOUS TRECONTACTOR IN SENTATIVE FOR IN	
S NO	E COTHE	
CENEA	SEMIK	
DEVIC PLAN		
THIS DEVICE PLEA		

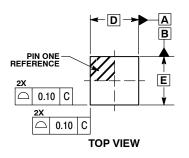
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

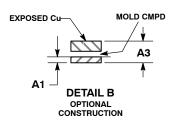


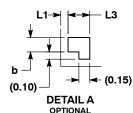


UQFN8, 1.60x1.60, 0.50P CASE 523AN **ISSUE O**

DATE 26 NOV 2008





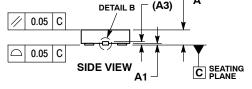


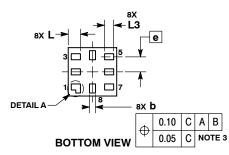
CONSTRUCTION

NOTES:

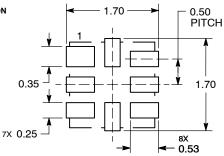
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS. DIMENSION 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

	MILLIMETERS						
DIM	MIN	MAX					
Α	0.45	0.60					
A1	0.00	0.05					
А3	0.13	REF					
b	0.15	0.25					
D	1.60 BSC						
Е	1.60 BSC						
е	0.50	BSC					
L	0.35	0.45					
L1		0.15					
L3	0.25	0.35					





SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XX = Specific Device Code

= Date Code

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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